

IN THE CLAIMS:

1. - 8. (Cancelled)

9. (Previously presented) A semiconductor package, comprising:
an intermediate lead finger mounting substrate having a first surface and a second surface;
a semiconductor die with a bond pad, the semiconductor die being attached on the first surface of the intermediate lead finger mounting substrate;
a package lead;
a bond wire comprising a first end portion coupled to the package lead, a second end portion coupled to the bond pad, and an intermediate portion;
an intermediate lead finger mounted on the first surface of the intermediate lead finger mounting substrate, wherein the intermediate lead finger is positioned between the package lead and the bond pad, and wherein the intermediate lead finger is attached to the intermediate portion of the bond wire, and remains so attached through a subsequent molding process;
a heat sink coupled to the second surface of the intermediate lead finger mounting substrate; and
a mold compound that encloses the semiconductor die, a portion of the package lead, the bond wire, the intermediate lead finger, and the heat sink.

10. (Original) The package of claim 9, wherein the intermediate lead finger and the intermediate lead finger mounting substrate are formed of a non-conducting material.

11. (Original) The package of claim 9, wherein the intermediate lead finger comprises a non-conducting portion for attaching to the intermediate portion of the bond wire.

12. (Original) The package of claim 9, wherein the semiconductor die comprises a programmable logic device.

13. (Original) The package of claim 9, wherein the semiconductor die is mounted on a center portion of the first surface of the intermediate lead finger mounting substrate, and

wherein the intermediate lead finger is mounted on a peripheral portion of the first surface of the intermediate lead finger mounting substrate.

14. – 27. (Cancelled)